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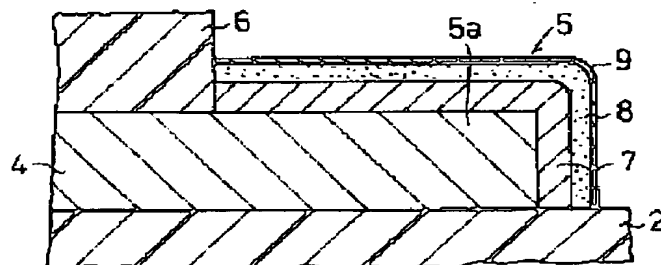
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APPLICANT : IBIDEN CO LTD;

INVENTOR : OKUDA YASUHIRO;

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TITLE : BONDING PAD FOR PRINTED WIRING
BOARD AND ELECTROLESS GOLD
PLATING METHOD FOR CONDUCTOR
PATTERN



ABSTRACT : PURPOSE: To provide a bonding pad for a printed wiring board and a method for forming a gold conductor pattern by electroless plating which has excellent bondability of a gold wire and a low manufacturing cost.

CONSTITUTION: An area unnecessary for gold plating of a conductor pattern 4 formed on a surface of a board 2 is coated with a solder resist 6. An amorphous first electroless nickel film 7 is formed on the pattern 4 not coated with the resist 6 by electroless nickel plating. Then, a crystalline second electroless nickel film 8 containing 3-8% of phosphorus content is formed on a surface of the film 7 by electroless nickel plating. Thereafter, an electroless gold plating film 9 is formed on a surface of the film 8 by electroless gold plating in which substitution reaction is the main reaction.

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